

TF-3050

SERIES 2 LDP10TQ THICK FILM CHIP TRIMMER



A New Generation Platform for Trim and Test Thick Film Chip Components

- Capability to trim from milli-ohms (mΩ) to Mega-ohms (MΩ)
- Ability to trim substrates with resistors up to size 0.04"X0.02"
- Fully redefined user friendly GUI software
- Theta adjustment for clamping device for precise alignment
- Twin magazines to store additional substrates and reduce machine idle time.

TF-3050 SERIES 2 LDP10TQ THICK FILM CHIP TRIMMER - SPECIFICATIONS

Optical System

- **Beam Positioned:** Precision high-speed galvanometer
- **Field Size:** 12 x 90mm
- **Resolution:** 1.5μm
- **Repeatability:** 2.5 μm
- **Spot Size:** 18 - 40 μm (standard 1064nm)
- **Focus Len:** 125 mm flat telecentric type

Laser System

- **Laser Type:** Diode pumped ND: YAG Lasers
- **Output Power:** 6W (Q-Switched Avg. Power @ 10 KHz)
- **Wavelength:** Standard 1064nm
- **Pulse Width, nominal:** 150 nsec
- **Power Measurement:** Thermal pickup

X/Y Part Positioning

- **Type:** Dual carriage system with high speed motor
- **X Axis:** Driven by high speed linear motor (carriages) - Resolution: 1μm
- **Travel Speed:** 600 mm/s
- **Prober & Axis:** DC brushless servo motor
- **Theta Control:** Motorized theta control
- **Part Transfer:** AC motor controlled pick and place arms
- **Part Load/Unload:** Dual magazines with elevators

Software

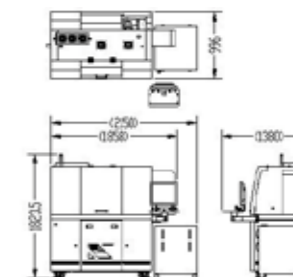
- DOS Application Software
- WinLts 2 Windows XP Application Software (optional)

Measurement System

- **Dual Mode:** Force Current & Force Voltage
- **Range:** 0.1Ω ~ 30 MΩ, 10 mΩ Optional
- **Accuracy:** 0.02% Midrange
- **Repeatability:** 0.01% Midrange
- **Resolution:** 0.005%
- **Measurement Time:** 50 μsec
- **Calibration Standards:** 6 pcs 0.01%
- **Guard Drive Current:** 100 mA
- **Guard Offset:** 1 mV

Physical Characteristics

- **Dimensions:** 2125 mm x 966 mm x 1858 mm
- **Weight:** 1000kg



Utilities Requirements

- **Power:** 220 V AC, single phase, 10A (50/60Hz)
- **Air:** 80~100 psi / flow rate 10 cfm
- **Vacuum:** 100 CFM factory vacuum for debris removal and substrates retention

Note: Laser Power supply not included.

Controller

- Intel Core 2 duo processor for Windows main application (Optional)
- Pentium processor for trimmer application and motion control

Special Features

- Dual magazine with two sets of magazines to reduce the machine idle time
- Improved pick up arm for efficient pick up and placing of substrates
- Completely redesigned GUI improves machine productivity (Optional)

Switching Matrix

- **Pins per Card:** 16
- **Lines per Pin:** 3 (Force, Sense or Guard)
- **Cards per System (Standard):** 10 pcs std, 12 pcs maximum
- **Switch Type:** Dry Reed Relay
- **Contact Life:** 1 Billion Cycles
- **Insulation:** > 10 GΩ
- **Switching Time:** 200 μsec

 **LASER TEK** (SINGAPORE) PTE LTD
雷科(新)私人有限公司

Laser Tek Singapore Pte. Ltd.
33 Ubi Avenue 3, #02-42/43, Vertex,
Singapore 408868
Tel: (65) 6742 8260 Fax (65) 6742 3719
<http://www.lasertek.com.sg>

 **LASER TEK** TAIWAN Co. LTD
雷科控股有限公司

Laser Tek Taiwan Co., Ltd
No. 248-12, Shin Sheng Rd., Chien-Zhen District,
Kaoshiung, Taiwan 806, R.O.C.
Tel: 886-07-8159877 Fax: 886-07-8156711
<http://www.lasertek.com.tw>